

Claims:

1. An apparatus for processing substrates, comprising:  
2      a) a transfer chamber;  
3      b) one or more load lock chambers connected to the transfer chamber;  
4      c) one or more process chambers connected to the transfer chamber;  
5      d) a modular plumbing tray disposed adjacent the transfer chamber and  
6 having facility connections for one or more of the process chambers and the load lock  
7 chambers; and  
8      e) a chamber tray disposed adjacent the one or more of the process  
9 chambers, load lock chambers and transfer chamber, the chamber tray having facility  
10 connections connected to one or more facility connections in the plumbing tray.
- 1 2. A method of processing a substrate, comprising:  
2      a) introducing a substrate into a load lock chamber from atmospheric  
3 pressure;  
4      b) degassing and/or pre-heating the substrate in the load lock chamber;  
5      c) introducing the substrate into a transfer chamber; and  
6      d) processing the substrate in one or more process chambers.
- 1 3. The method of claim 2 further comprising:  
2      e) introducing the substrate into the load lock chamber;  
3      f) cooling the substrate in the load lock chamber; and then  
4      g) venting the load lock chamber to atmospheric pressure.
- 1 4. An apparatus for distributing facility to devices on a processing system,  
2 comprising:  
3      a) an enclosure having at least one facility interface and one or more  
4 chamber interfaces; and

5           b)     one or more of a process gas manifold, vacuum manifold, water  
6     manifold and a helium manifold disposed in the enclosure connected between the at  
7     least one facility interface and the one or more chamber interfaces.

1     5.     An apparatus for distributing facility, comprising:  
2       a)     a support frame having one or more of an electronics box, a gas panel, a  
3     vacuum line and a controller device disposed thereon.

1     6.     A method of processing substrates, comprising:  
2       a)     positioning a pair of substrates on two blades on separate robots in a  
3     processing system;  
4       b)     moving the substrates in parallel to a pair of first process chambers; and  
5     then  
6       c)     moving the substrates in parallel to a pair of second process chambers.

